

HIGH TEMP AEC-Q200 INDUCTORS - ECM9070FBQ1 SERIES



●FEATURE

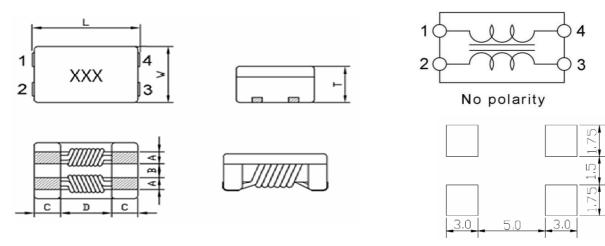
- 1. Capable of handling the highest current(up to 5A) of any chip-type common mode filter
- 2. Noise is greatly suppressed.
- 3. AEC-Q200 Qualified

Applications

- 1. Used for power line noise suppression for any electric devices. Used to counter adapter/battery line noise for relatively large electronic devices such as notebook, stand-alone word processor, etc.
- 2. Same as TDK ACM9070 series

Shape and Dimension

Schematics and Land Patterns(mm)



 $L=9.00\pm0.50 \text{ m/m}$; $W=7.00\pm0.50 \text{ m/m}$; T=4.80 m/m Max; A=1.50 m/m Ref.; B=2.00 m/m

Ref. C=1.70 m/m Ref.; D=5.70 m/m Ref.; Black cover

Specification

	Common mod	de Impedance	DC Resistance	Rated	Rated	Insulation
Part number	ber Z(Ω) at 100MHz		(mΩ Max)	Current(A)	Voltage(V)	Resistance
	min	typical				(MΩ)Min
ECM9070FBQ1-301	225	300	6	6	80	10
ECM9070FBQ1-501	350	500	8	6	80	10
ECM9070FBQ1-701	500	700	10	5	80	10
ECM9070FBQ1-102	750	1000	13	4	80	10
ECM9070FBQ1-152	1300	1500	50	3	80	10

Note1. Measurement ambient temperature of Impedance, DCR and IDC : at 25 $^{\circ}\! \text{C}$

Note2. Packing: reel; Quantity: 700pcs/reel



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GENERAL CHARACTERISTICS

- 1. Operating temperature range: -40 TO + 125°C (Includes temperature when the coil is heated)
- 2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 125°C). Part can be stored for 1000 hrs @125°C. Unpowered. Measurement at 24±4 hours after test conclusion.
- 3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-40 TO + 125℃). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
- 4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85[°]C/85[°]RH. Unpowered. Measurement at 24±4 hours after test conclusion.
- 5. Operational Life refer MIL-PRF-27: 1000 hrs. at 125 °C tested. Measurement at 24±4 hours after test conclusion.
- 6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
- 7. Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
- 8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical OKEM clean or equivalent.
- 9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
- 10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
- 11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
- 12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
- 13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235℃,category 3; SMD, a)Method B, 4hrs@125℃ dry heat @235℃, b)Method B@215℃ category 3., c)Method D category 3@260℃
- 14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
- 15. Flammability refer UL-94: V-0 or V-1 Acceptable.
- 16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
- 17. Terminal Strength(SMD) refer AEC-Q200-006